

Revision:	Date:	Description:	Prepared:	Notes:  Function test: no open, no short circuit, no intermittent						
Α	9/26/2018	Initial release	AW Digitally signed by AW Date: 2018.09.27 12:29:50-07'00'				$\vdash$	NSII ITY		
			Verified: JP  Depart of the 2014 (2012)  Dimensions are in			tel 1.541.323.3228 800 877.670.7118 fax 1.541.323.4202 web tensility.com				
			millimeters. Tolerances: < 1.0: ± 0.1 mm	Description: Connector, dc jack 5.5x2.5 mm, PCB mount, 90°,	Size:					
			1.0 to 10.0: ± 0.2 mm > 10.0: ± 0.3 mm	silver plated, board lock		Scale:	3:1		Sheet 1 of 2	
		5	4	3	2	•			1	

## Ratings

Maximum operating voltage: 48 V

Maximum operating current: 6 A (not mated under load)

## **Operating Temperature Range**

-25 ~ 85 °C, relative humidity of 85% or less

### Materials

1)Insulator: PBT, black

(2) Cover: PBT, black (3) Center Pin: copper alloy, nickel plated

(4)Spring contact: phosphor bronze, silver plated

5)Terminal: brass, silver plated

(6)Terminal: brass, silver plated

## **Electrical Requirements**

Dielectric strength: 1 min @ 500 Vac Insulation resistance: 100 MΩ @ 500 Vdc minimum

Contact resistance: 50 mΩ maximum

## **Mechanical Requirements**

Insertion force: 0.7-1.5 kgf

Withdrawal force: 0.5-1.5 kgf

Life cycle: 5000 mating cycles while maintaining contact resistance: 100 mΩ maximum, withstand voltage: 500 Vac, 1 min

Terminal strength: 150 gf applied to the terminal for 15 seconds in any direction while maintaining electrical characteristics and without damage or excessive looseness of terminals

## Soldering

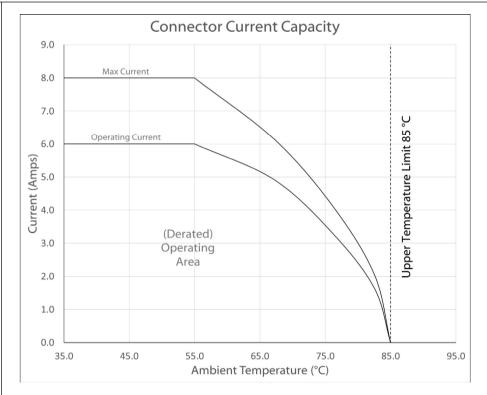
Solderability: 75% minimum coverage when terminals dipped 2mm in 245 ±5 °C solder bath for 3 ±0.5 seconds

Solder bath durability: no deformation when immersed in 255  $\pm$ 5 °C up to surface of the board 1.6 mm for 5 seconds or less

Solder iron durability: no deformation when exposed to  $350 \pm 10$  °C for 3 ±0.5 seconds

**Environmental Requirements** Cold test: -25 ±3 °C for 48 hours without deformation Heat test:  $85 \pm 2$  °C, relative humidity 45-85% for 48 hours without deformation

Humidity test:  $40 \pm 2$  °C, relative humidity 90-95% for 48 hours without deformation



Testing based on IEC 60512-5-2. Max current curve generated with isolated test article under controlled environmental conditions, and does not take into account external factors such as housings, mating cables, or other circuitry. Operating current curve (derated by 20% of maximum values) accounts for external factors, and manufacturing variation.

# **Wave Soldering Temperature Profile**

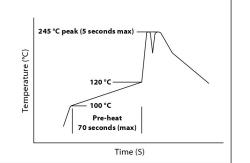
Pb - Free Flow Profile

Solder temperature: 245 °C

Time: 5 seconds maximum

Pre-heat: 100 ~120°C Time: 70 seconds maximum

Measure point: surface of the solder leads



Revision: Date: Des		Prepared:	Notes:					
A 9/26/2018 Initi	itial release	AW Digitally signed by Date: 2018.09.27 12:30:05 -07'00'	Function test: no open, no short	circuit, no		FNSII ITY		
		Verified:	intermittent		•			
		JP Digitally signed by JP Date: 2018.09.27 13:50:24-07'00'			tel 1.541.323.3228 800 877.670.7118			
		Dimensions are in			fax 1.541.323.4202 web tensility.com			
		millimeters. Tolerances:	Description: Connector, dc jack 5.5x2.5 mm, PCB mount, 90°, silver plated, board lock		Size: Part number:			
		$< 1.0: \pm 0.1 \text{ mm}$			Α	A 54-00132		
		1.0 to 10.0: ± 0.2 m > 10.0: ± 0.3 mm			Scale:	1:1 Sheet 2 of 2		